

MOSFET - Power, Single N-Channel SuperFET® V, FRFET®, D²PAK 600 V, 55 m Ω , 45 A NVB055N60S5F

Description

The SUPERFET V MOSFET FRFET series has optimized body diode performance characteristics. This can allow for the removal of components in the application and improve application performance and reliability, particularly when soft switching topologies are used.

Features

- 650 V @ T_J = 150°C / $Typ.~R_{DS(on)}$ = 44 $m\Omega$
- 100% Avalanche Tested
- Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Electric Vehicle On Board Chargers
- EV Main Battery DC/DC Converters

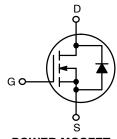
MAXIMUM RATINGS (T_{.I} = 25°C unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain-to-Source Voltage	V_{DSS}	600	V	
Gate-to-Source Voltage	DC		±30	V
	AC (f > 1 Hz)		±30	
Continuous Drain Current	T _C = 25°C	I _D	45	Α
	T _C = 100°C		28	
Power Dissipation	T _C = 25°C	P_{D}	278	W
Pulsed Drain Current	T 25°C	I _{DM}	159	Α
Pulsed Source Current (Body Diode)	T _C = 25°C, t _P = 10 μs	I _{SM}	159	
Operating Junction and Storage Range	T _J , T _{stg}	-55 to +150	°C	
Source Current (Body Diode)	Source Current (Body Diode)			Α
Single Pulse Avalanche Energy	$(I_L = 7 A,$ $R_G = 25 \Omega)$	E _{AS}	417	mJ
Avalanche Current	I _{AS}	7	Α	
Repetitive Avalanche Energy (N	E _{AR}	2.78	mJ	
MOSFET dv/dt	dvdt	120	V/ns	
Peak Diode Recovery dv/dt (Not		70		
Lead Temperature for Soldering (1/8" from case for 10 s)	TL	260	°C	

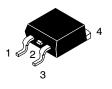
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. $I_{SD} \le 22.5$ A, di/dt ≤ 200 A/ μ s, $V_{DD} \le 400$ V, starting $T_J = 25$ °C.

V _{DSS}	R _{DS(ON)} MAX	I _D MAX	
600 V	55 mΩ @ 10 V	45 A	

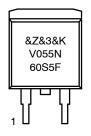


POWER MOSFET



D²PAK CASE 418AJ

MARKING DIAGRAM



&Z = Assembly Plant Code &3 = Date Code (Year & Week) &K = Assembly Lot V055N60S5F = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

THERMAL RESISTANCE

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case, Max.	$R_{ heta JC}$	0.45	°C/W
Thermal Resistance, Junction-to-Ambient, Max.	$R_{ heta JA}$	62.5	

ELECTRICAL CHARACTERISTICS (T₁ = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS					-	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	600	_	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	ΔV _{(BR)DSS} / ΔT _J	I _D = 10 mA, Referenced to 25°C	-	581	-	mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 600 V, T _J = 25°C	-	-	10	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA
ON CHARACTERISTICS						
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 22.5 A, T _J = 25°C	-	44	55	mΩ
Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}$, $I_D = 5.2$ mA, $T_J = 25^{\circ}C$	3.2	-	4.8	V
Forward Trans-conductance	9FS	V _{DS} = 20 V, I _D = 22.5 A	-	44.8	_	S
CHARGES, CAPACITANCES & GATE	RESISTANCE					
Input Capacitance	C _{ISS}	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 250 \text{ kHz}$	-	4603	_	pF
Output Capacitance	C _{OSS}		-	72.9	_	1
Time Related Output Capacitance	C _{OSS(tr.)}	I_D = Constant, V_{DS} = 0 V to 400 V, V_{GS} = 0 V	-	1114	-	
Energy Related Output Capacitance	C _{OSS(er.)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	125	_	1
Total Gate Charge	Q _{G(tot)}	$V_{DD} = 400 \text{ V}, I_D = 22.5 \text{ A}, V_{GS} = 10 \text{ V}$	-	85.2	_	nC
Gate-to-Source Charge	Q_{GS}		-	26.2	_	1
Gate-to-Drain Charge	Q_{GD}		-	24.9	_	1
Gate Resistance	R_{G}	f = 1 MHz	-	4.32	_	Ω
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t _{d(on)}	$V_{GS} = 0/10 \text{ V}, V_{DD} = 400 \text{ V},$	-	44	_	ns
Rise Time	t _r	$I_D = 22.5 \text{ A}, R_G = 4.7 \Omega$	-	26.2	_	1
Turn-Off Delay Time	t _{d(off)}	1	-	108	-	1
Fall Time	t _f	<u> </u>	-	2.6	_	
SOURCE-TO-DRAIN DIODE CHARAC	TERISTICS		_		_	
Forward Diode Voltage	V_{SD}	$V_{GS} = 0 \text{ V}, I_{SD} = 22.5 \text{ A}, T_J = 25^{\circ}\text{C}$	-	-	1.2	V
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V}, I_{SD} = 22.5 \text{ A},$	-	128	-	ns
Reverse Recovery Charge	Q _{RR}	dl/dt = 100 A/μs, V _{DD} = 400 V	-	758	-	nC

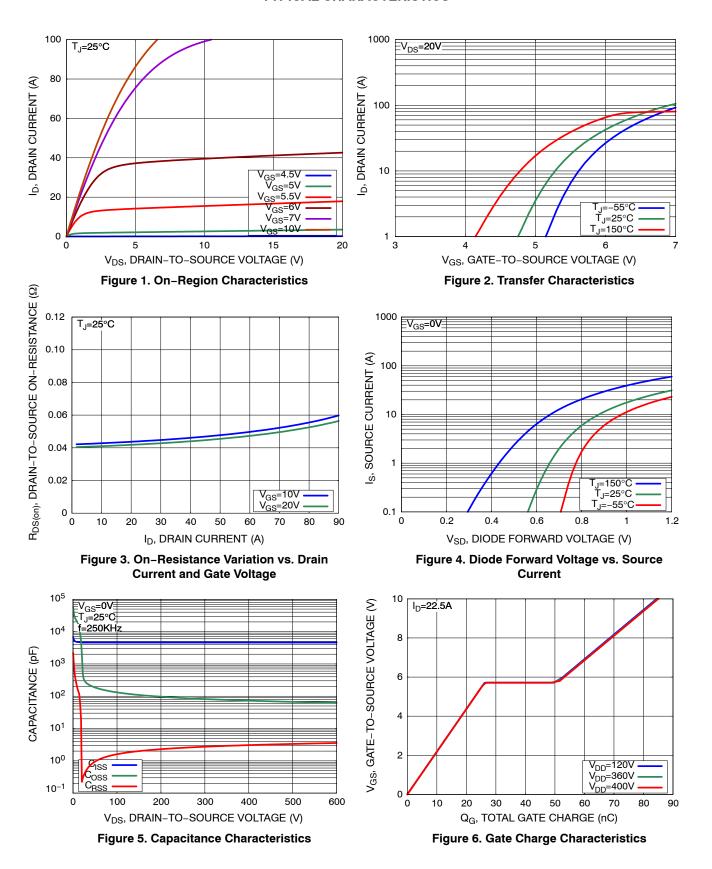
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NVB055N60S5F	V055N60S5F	D ² PAK	Tape & Reel [†]	330 mm	24 mm	800 Units

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

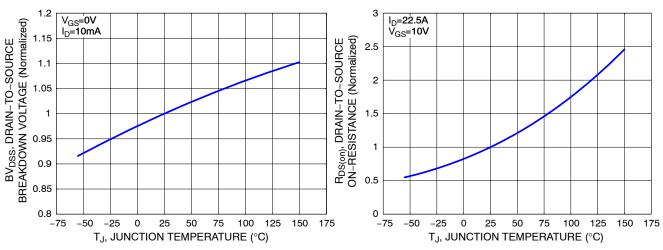


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On–Resistance Variation vs.
Temperature

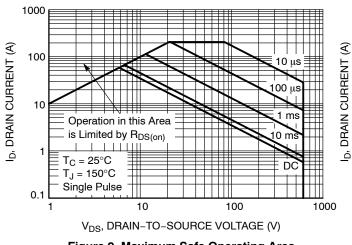


Figure 9. Maximum Safe Operating Area

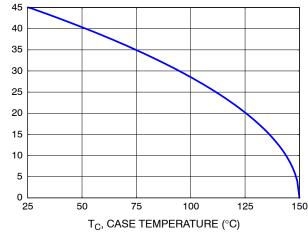


Figure 10. Maximum Drain Current vs. Case Temperature

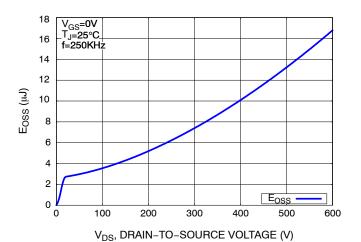


Figure 11. E_{OSS} vs. Drain-to-Source Voltage

TYPICAL CHARACTERISTICS

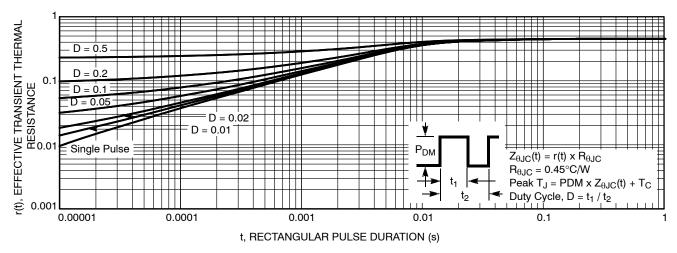


Figure 12. Transient Thermal Impedance

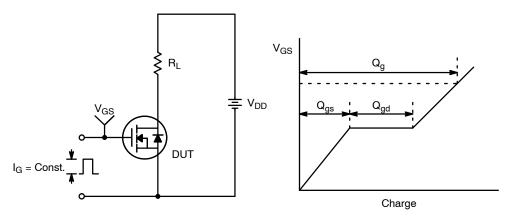


Figure 13. Gate Charge Test Circuit & Waveform

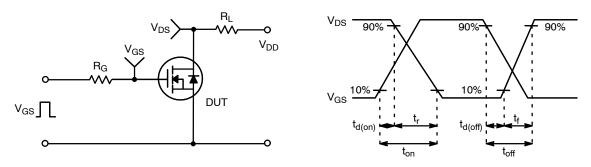


Figure 14. Resistive Switching Test Circuit & Waveforms

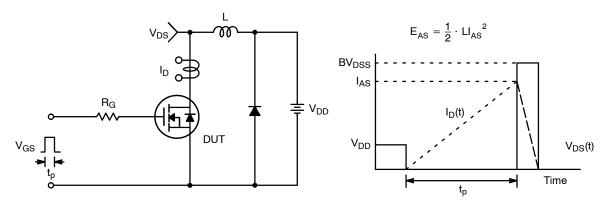


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

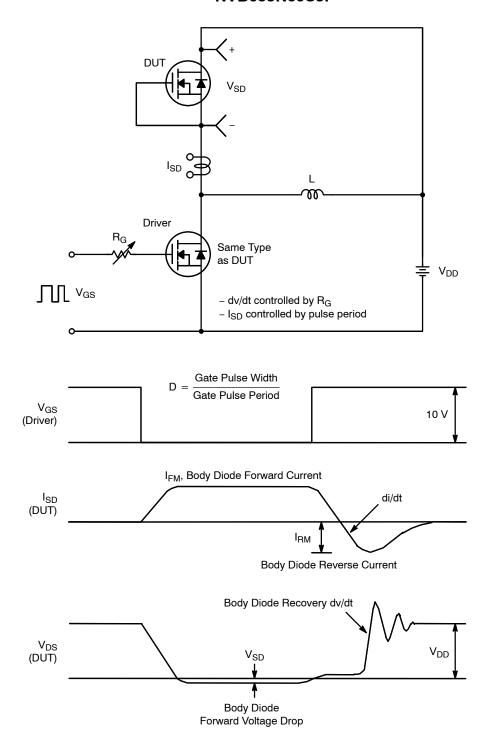
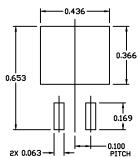


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



D²PAK-3 (TO-263, 3-LEAD) CASE 418AJ ISSUE F

DATE 11 MAR 2021



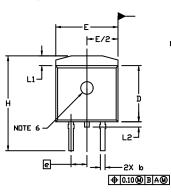
RECOMMENDED MOUNTING FOOTPRINT

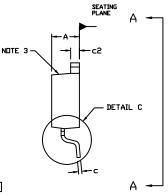
For additional information on our Pb-Free strategy and soldering details, please download the IN Seniconductor Soldering and Mounting Techniques Reference Manual, SILIERRM/D.

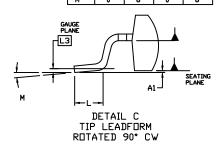
NOTES

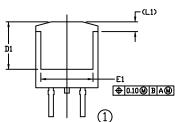
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: INCHES
- 3. CHAMFER OPTIONAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH.
 MOLD FLASH SHALL NOT EXCEED 0.005 PER SIDE.
 THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST
 EXTREMES OF THE PLASTIC BODY AT DATUM H.
- 5. THERMAL PAD CONTOUR IS OPTIONAL WITHIN DIMENSIONS E, L1, D1, AND E1.
- 6. OPTIONAL MOLD FEATURE.
- 7. ①,② ... DPTIONAL CONSTRUCTION FEATURE CALL DUTS.

	INCHES		MILLIN	METERS	
DIM	MIN.	MAX.	MIN.	MAX.	
Α	0.160	0.190	4.06	4.83	
A1	0.000	0.010	0.00	0.25	
b	0.020	0.039	0.51	0.99	
С	0.012	0.029	0.30	0.74	
c2	0.045	0.065	1.14	1.65	
D	0.330	0.380	8.38	9.65	
D1	0.260		6.60		
E	0.380	0.420	9.65	10.67	
E1	0.245		6.22		
e	0.100 BSC		2.54 BSC		
Н	0.575	0.625	14.60	15.88	
L	0.070	0.110	1.78	2.79	
L1		0.066		1.68	
L5		0.070		1.78	
L3	0.010 BSC		0.25	BSC	
м	0+	8*	n•	8.	

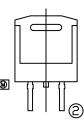


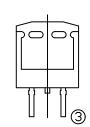


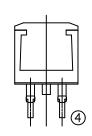




VIEW A-A







VIEW A-A

OPTIONAL CONSTRUCTIONS

GENERIC MARKING DIAGRAMS*

XXXXXX = Specific Device Code A = Assembly Location

 WL
 = Wafer Lot

 Y
 = Year

 WW
 = Work Week

 W
 = Week Code (SSG)

 M
 = Month Code (SSG)

 G
 = Pb-Free Package

 AKA
 = Polarity Indicator

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present. Some products may not follow the Generic Marking.

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98AON56370E

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DESCRIPTION:

D²PAK-3 (TO-263, 3-LEAD)

PAGE 1 OF 1

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